

Claims (not amended herein):

1. (Previously presented) A light emitting package comprising:
 - a chip carrier having top and bottom principal surfaces;
 - at least one light emitting chip attached to the top principal surface of the chip carrier; and
 - a lead frame attached to the top principal surface of the chip carrier but not to the bottom principal surface of the chip carrier.
2. (Original) The light emitting package as set forth in claim 1, further comprising:
 - an encapsulant encapsulating at least the light emitting chip and the top principal surface of the chip carrier, the bottom principal surface of the chip carrier and leads of the lead frame extending outside the encapsulant.
3. (Original) The light emitting package as set forth in claim 1, further comprising:
 - one or more areas of electrically conductive material disposed on the top principal surface of the chip carrier, the attachment of the lead frame to the top principal surface electrically contacting the one or more areas of electrically conductive material.
4. (Original) The light emitting package as set forth in claim 3, wherein the one or more areas of electrically conductive material include:
 - a first area of electrically conductive material defining a first electrical terminal;
 - a second area of electrically conductive material electrically isolated from the first area, the second area defining a second electrical terminal of opposite electrical polarity from the first electrical terminal;
 - electrodes of the light emitting chip being electrically connected with the first and second electrical terminals; and
 - the lead frame being attached to the first and second electrical terminals.

5. (Original) The light emitting package as set forth in claim 4, wherein the light emitting chip is flip-chip bonded to the first and second electrical terminals.

6. (Original) The light emitting package as set forth in claim 4, wherein the light emitting chip is flip-chip bonded to the first and second electrical terminals using one of thermosonic bonding, solder, and a conductive epoxy.

7. (Original) The light emitting package as set forth in claim 4, wherein at least one electrode of the light emitting chip is wire bonded to one of the first and second electrical terminals.

8. (Original) The light emitting package as set forth in claim 7, wherein another electrode of the light emitting chip is wire bonded to the other one of the first and second electrical terminals.

9. (Original) The light emitting package as set forth in claim 3, wherein:
the one or more areas of electrically conductive material include:

 a first area of electrically conductive material defining a first electrical terminal,

 a second area of electrically conductive material electrically isolated from the first area, the second area defining a second electrical terminal of opposite electrical polarity from the first electrical terminal, and

 a third area of electrically conductive material electrically isolated from the first and second areas of electrically conductive material, the third area of electrically conductive material defining a series interconnection terminal; and

the light emitting chip includes first and second light emitting chips, electrodes of the first light emitting chip being electrically connected with the first and series interconnection electrical terminals and electrodes of the second light emitting chip being electrically connected with the second and series interconnection electrical terminals, and the lead frame being attached to the first and second electrical terminals.

10. (Original) The light emitting package as set forth in claim **9**, wherein the light emitting chip further includes:

a third light emitting chip, electrodes of the third light emitting chip being electrically connected with the first and series interconnection electrical terminals.

11. (Original) The light emitting package as set forth in claim **10**, wherein the light emitting chip further includes:

a fourth light emitting chip, electrodes of the fourth light emitting chip being electrically connected with the second and series interconnection electrical terminals.

12. (Original) The light emitting package as set forth in claim **9**, further including:

at least one zener diode electrically connected with at least one of
the first and series interconnection electrical terminals, and
the second and series interconnection electrical terminals.

13. (Original) The light emitting package as set forth in claim **3**, further including:

at least one electronic component electrically contacting the one or more areas of electrically conductive material, the at least one electronic component regulating behavior of the at least one light emitting chip.

14. (Original) The light emitting package as set forth in claim **13**, wherein the at least one electronic component includes:

a zener diode electrically connected in parallel with the light emitting chip to provide electrostatic discharge protection.

15. (Original) The light emitting package as set forth in claim **1**, wherein the light emitting chip receives electrical power through the lead frame and does not receive electrical power through the bottom principal surface of the chip carrier.

16. (Original) The light emitting package as set forth in claim **1**, wherein the bottom principal surface of the chip carrier is electrically isolated from the lead frame.

17. (Original) The light emitting package as set forth in claim 1, wherein the lead frame has electrical leads extending from portions of the lead frame attached to the top principal surface of the chip carrier, the electrical leads being shaped to include lead portions approximately coplanar with the bottom principal surface of the chip carrier.

18. (Original) The light emitting as set forth in claim 17, wherein the bottom principal surface of the chip carrier is at least one of substantially electrically non-conductive and electrically isolated from the lead frame.

19. (Original) The light emitting package as set forth in claim 18, wherein the chip carrier, light emitting chip, and lead frame define a surface mountable unit, the light emitting package further comprising:

printed circuitry, the surface mountable unit being mounted on the printed circuitry with the lead portions approximately coplanar with the bottom principal surface of the chip carrier electrically contacting the printed circuitry.

20. (Original) The light emitting package as set forth in claim 19, further comprising:

a printed circuit board including the printed circuitry, the bottom principal surface of the chip carrier being in thermal contact with the printed circuit board.

21. (Previously presented) A light emitting package comprising:

a chip carrier having top and bottom principal surfaces;

at least one light emitting chip attached to the top principal surface of the chip carrier;

a lead frame attached to the top principal surface of the chip carrier, the lead frame having electrical leads extending from portions of the lead frame attached to the top principal surface of the chip carrier, the electrical leads being shaped to include lead portions approximately coplanar with the bottom principal surface of the chip carrier;

wherein the bottom principal surface of the chip carrier is at least one of substantially electrically non-conductive and electrically isolated from the lead frame

and the chip carrier, light emitting chip, and lead frame define a surface mountable unit;

a printed circuit board on which the printed circuitry is disposed, the surface mountable unit being mounted on the printed circuitry with the lead portions approximately coplanar with the bottom principal surface of the chip carrier electrically contacting the printed circuitry, the bottom principal surface of the chip carrier being in direct contact with the printed circuit board.

22. (Original) The light emitting package as set forth in claim **21**, wherein the chip carrier is soldered to the printed circuit board.

23. (Original) The light emitting package as set forth in claim **21**, wherein the chip carrier is soldered to the printed circuit board, said soldered connection being thermally conductive but not conducting electrical current when the light emitting chip is operated.

24. (Original) The light emitting package as set forth in claim **21**, wherein an attachment between the lead portions contacting the printed circuitry is different from an attachment of the bottom principal surface of the chip carrier contacting the printed circuit board.

25. (Original) The light emitting package as set forth in claim **21**, further comprising:

an encapsulant encapsulating at least the light emitting chip and the top principal surface of the chip carrier, the bottom principal surface of the chip carrier and at least the lead portions approximately coplanar with the bottom principal surface of the chip carrier extending outside the encapsulant.

26. (Original) The light emitting package as set forth in claim **1**, wherein the chip carrier comprises:

a semi-insulating silicon wafer.

27. (Original) The light emitting package as set forth in claim 1, wherein the chip carrier comprises:

electrically conductive silicon having at least the top principal surface coated with an insulating layer.

28. (Original) The light emitting package as set forth in claim 1, wherein the chip carrier comprises:

metal having at least the top principal surface coated with an insulating layer.

29. (Original) The light emitting package as set forth in claim 1, wherein the chip carrier comprises:

thermally conductive plastic.

30. (Original) The light emitting package as set forth in claim 1, wherein the chip carrier comprises:

ceramic.

31. (Original) The light emitting package as set forth in claim 1, wherein the chip carrier is electrically insulating and the lead frame is electrically conductive.

32-37. (Canceled)

38. (Previously presented) The light emitting package as set forth in claim 1, wherein the lead frame includes electrical leads extending from portions of the lead frame attached to the top principal surface of the chip carrier, the electrical leads being shaped to include lead portions distal from the chip carrier that are approximately coplanar with the bottom principal surface of the chip carrier.

39. (Previously presented) A light emitting package comprising:

a chip carrier having top and bottom principal surfaces;

at least one light emitting chip attached to the top principal surface of the chip carrier; and

a lead frame attached to the top principal surface of the chip carrier, the lead frame including electrical leads extending from portions of the lead frame attached to the top principal surface of the chip carrier, the electrical leads being shaped to include lead portions extended away from the chip carrier that are approximately coplanar with the bottom principal surface of the chip carrier.

40. (Previously presented) The light emitting package as set forth in claim **1**, further comprising:

solder bonds attaching the lead frame to the top principal surface of the chip carrier.

41. (Previously presented) The light emitting package as set forth in claim **39**, further comprising:

solder bonds attaching the lead frame to the top principal surface of the chip carrier.